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SH7263/SH7203 Group

Data Transfer between Memory Areas with DMAC

Introduction

This application note provides an example of transferring data between memory areas with the direct memory access controller (DMAC) of the SH7263/SH7203.

Target Device

SH7263/SH7203

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1. Introduction

1.1 Specification

- DMAC channel 0 is used to transfer data from the on-chip RAM to external memory. Data are transferred in cyclestealing mode.
- Auto-request mode (software transfer request) is used for requesting DMA transfer.

1.2 Module Used

• Direct memory access controller (DMAC channel 0)

1.3 Applicable Conditions

•	Microcontroller:	SH7263/SH7203	
٠	Operating Frequency:	Internal clock	200 MHz
		Bus clock	66.67 MHz
		Peripheral clock	33.33 MHz
٠	C Compiler:	SuperH RISC eng	ine family C/C++ compiler package Ver.9.01, from Renesas
		Technology	
٠	Compile Option:		ou = single -include = "\$(WORKSPDIR)\inc"
		-object = "\$(CON	FIGDIR)\\$(FILELEAF).obj" -debug -gbr = auto -chgincpath
		-errorpath -global	_volatile = 0 -opt_range = all -infinite_loop = 0 -del_vacant_loop = 0
		$-struct_alloc = 1 - 1$	nologo

1.4 Related Application Note

The operation of the reference program for this document was confirmed with the setting conditions described in the application note: *SH7263/SH7203 Initialization Example*. Please refer to the application note in combination with this one.



2. Description of Sample Application

In this sample application, the direct memory access controller (DMAC) is used to transfer data from the on-chip RAM to external memory.

2.1 Operational Overview of Module Used

When a DMA transfer request is made, the DMAC starts to transfer data in order of priority of channels. Then, it continues the transfer operation until transfer end condition is met. It has three transfer request modes: auto request, external request, and on-chip peripheral module request. The bus mode is selectable from burst mode and cycle-stealing mode.

An overview of the DMAC is provided in table 1. Also, a block diagram of the DMAC is shown in figure 1.

Item	Description
Number of channels	8 channels (CH0 to CH7) Only 4 channels (CH0 to CH3) can receive external requests.
Address space	4 Gbytes
Length of transfer data	Byte, word (2 bytes), longword (4 bytes), and 16 bytes (longword \times 4)
Maximum transfer count	16,777,216 (24 bits) transfers
Address mode	Single address mode and dual address mode
Transfer request	 Auto request, external request, and on-chip peripheral module request SH7203/SH7263 (SCIF: 8 sources, I²C3: 8 sources, ADC: 1 source, MTU2: 5 sources, CMT: 2 sources, USB: 2 sources, FLCTL: 2 sources, RCAN-TL1: 2 sources, SSI: 4 sources, SSU: 4 sources) SH7263 (SRC: 2 sources, ROM-DEC: 1 source, SDHI: 2 sources)
Bus mode	Cycle-stealing mode and burst mode
Priority level	Channel priority fixed mode and round-robin mode
Interrupt request	An interrupt request to the CPU is made when half or all of a transfer process is completed.
External request detection	DREQ input low/high level detection, rising/falling edge detection
Transfer request acknowledge signal/transfer end signal	Active levels for DACK and TEND can be set independently

 Table 1
 Overview of DMAC

Note: For details on the DMAC, refer to the section on the direct memory access controller in the SH7263/SH7203 Group Hardware Manual.



SH7263/SH7203 Group Data Transfer between Memory Areas with DMAC

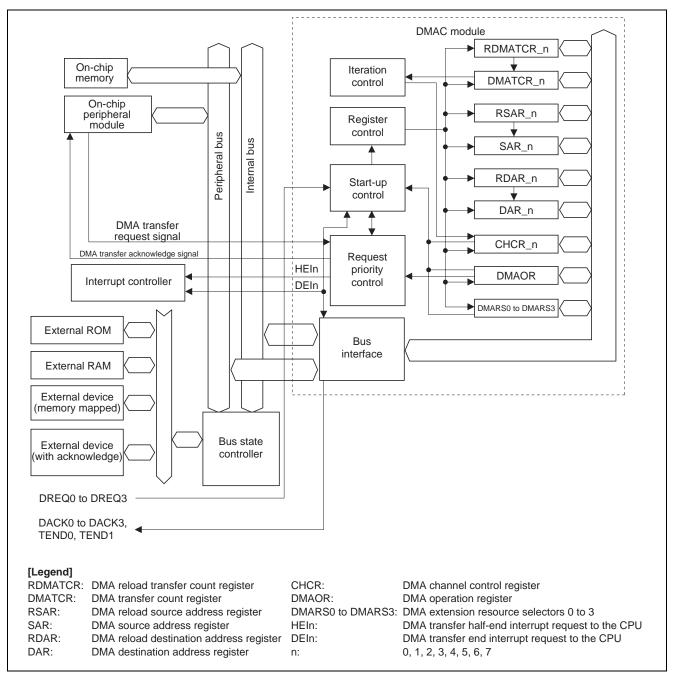
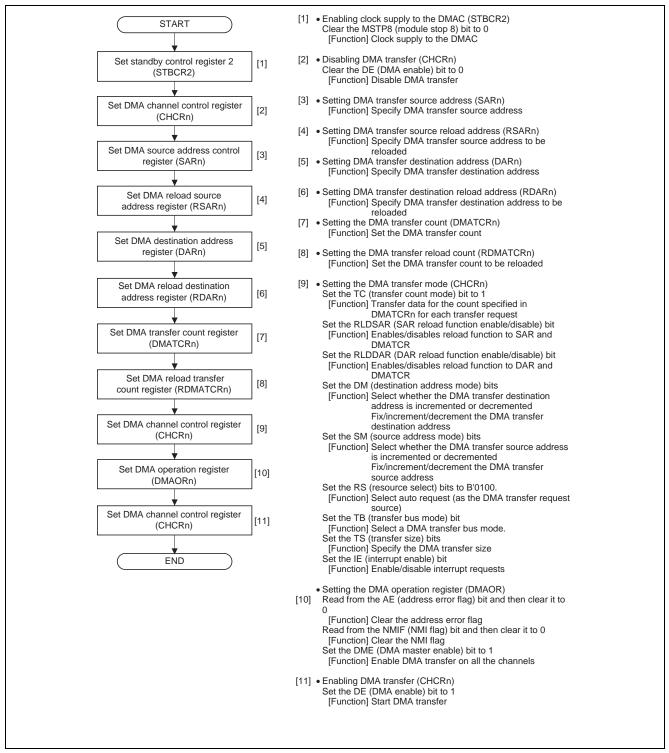


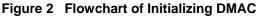
Figure 1 Block Diagram of DMAC

2.2 Procedure for Setting Module Used

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This section describes the procedure for specifying initial settings for transferring data between memory areas with the DMAC. Auto request mode is used for transfer requests. A flowchart of initializing the DMAC is shown in figure 2. For details on registers, refer to the *SH7263/SH7203 Group Hardware Manual*.





2.3 Operation of Sample Program

In this sample program, DMAC channel 0 is activated by auto request, and data are transferred from the on-chip RAM to external memory in cycle-stealing mode. In cycle-stealing transfer operation, the DMAC gives the bus mastership to the CPU after each round of transferring a single unit of data. An operation timing of the sample application is shown in figure 3.

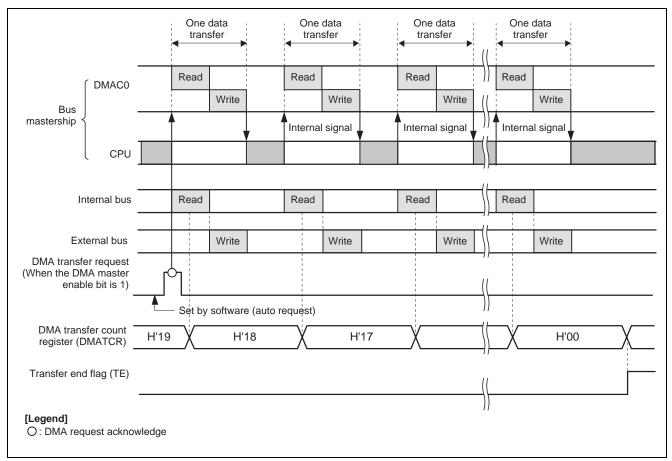


Figure 3 Operation Timing of Sample Application

2.4 Usage Notes on Sample Program

- In the reference program, the addresses where the source and destination areas of the transfer start are assigned as absolute addresses for clarity. Ensure that sections used by the user program do not overlap with the source and destination regions that start from the absolute addresses.
- In DMA transfer with operand cache enabled, coherency must be kept by disabling or writing back the cache. In the sample program, coherency is kept because a cache-disabled space is accessed from the CPU.

2.5 Processing Procedure of Sample Program

In this sample program 100-byte data stored in the on-chip RAM are transferred to external memory by DMA transfer. The transfer end flag (TE bit) is used to check whether DMA transfer is completed.

The register settings for the sample program are listed in table 2. The macro definitions used in this sample program are also listed in table 3. A flowchart of the sample program is illustrated in figure 4.

Register Name	Address	Setting Value	Description
Standby control register 2 (STBCR2)	H'FFFE 0018	H'00	MSTP8 = 0: DMAC operates
DMA channel control	H'FFFE 100C	H'0000 0000	DE = 0: Disables DMA transfer
register 0 (CHCR0)		H'8000 5410	TC = 1
			Transfers data for the count specified in DMATCR0 for each DMA transfer request RLDSAR = 0:
			Disables SAR reload function RLDDAR = 0:
			Disables DAR reload function
			DM = B'01: Increments destination address
			SM = B'01: Increments source address
			RS = B'0100: Auto request
			TB = 0: Cycle-stealing mode
			TS = B'10: Longword transfer
			IE = 0: Disables interrupt request
		H'8000 5411	DE = 1: Enables DMA transfer
DMA source address register 0 (SAR0)	H'FFFE 1000	H'FFF8 8000	Set start address of transfer source in an on-chip RAM area
DMA destination address register 0 (DAR0)	H'FFFE 1004	H'2C00 0000	Set start address of transfer destination in an external memory area*
DMA transfer count register 0 (DMATCR0)	H'FFFE 1008	H'64	Transfer count: 100 transfers (H'64)
DMA operation register (DMAOR)	H'FFFE 1200	H'0001	DME = 1: Enables DMA transfer on all the channels
DMA extension resource selector 0 (DMARS0)	H'FFFE 1300	H'0000 0000	Not used for auto request

Table 2 Register Settings for Sample Program

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Note: * The address of external memory varies depending on the target board to be used.



Table 3 Macro Definitions Used in Sample Program

Macro Definition	Setting Value	Description
SDRAM_DST_ADR	H'2C00 0000	Start address of SDRAM
SRAM_SRC_ADR	H'FFF8 8000	Start address of on-chip RAM
SIZE	H'64	Transfer count
DMA_SIZE_BYTE	H'0000	Byte transfer
DMA_SIZE_WORD	H'0001	Word transfer
DMA_SIZE_LONG	H'0002	Longword transfer
DMA_SIZE_LONGx4	H'0003	16-byte transfer
DMA_INT_DISABLE	H'0000	DMA transfer end interrupt disabled
DMA_INT_ENABLE	H'0010	DMA transfer end interrupt enabled

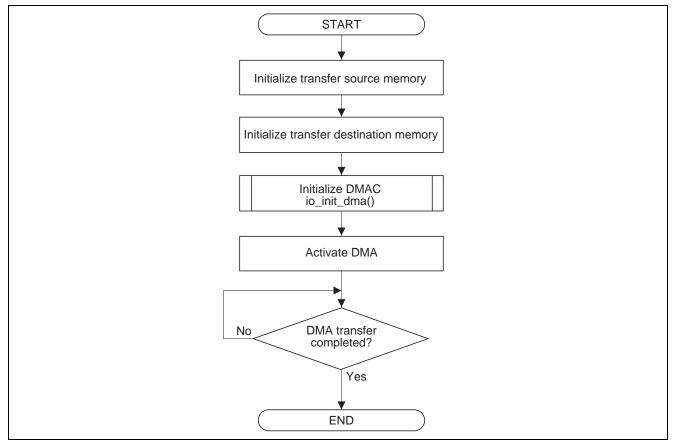


Figure 4 Flowchart of Sample Program



3. Sample Program

```
1. Sample Program Listing "main.c" (1)
```

```
2 *
3 *
          System Name: SH7203 Sample Program
4 *
          File Name : main.c
5 *
          Contents
                    : Data transfer between memory areas with DMAC
          Version
6 *
                    : 1.00.00
         Model
7 *
                   : M3A-HS30
8 *
         CPU
                    : SH7203
9 *
         Compiler : SHC9.1.1.0
10*
         note
                   : A sample program for transferring data with the DMACO.
11*
                     Using software triggers transfers 100-byte data from the on-chip RAM to
12*
                     external memory.
13*
14*
                    <Caution>
15*
                    This sample program is for reference
16*
                    and its operation is not guaranteed.
17*
                    Customers should use this sample program for technical reference
18*
                    in software development.
19*
20*
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          typographical errors. Renesas Technology Corporation and Renesas Solutions
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         AND Renesas Solutions Corp. All Rights Reserved
27*
28*
         history
                   : 2007.12.27 ver.1.00.00
30#include <stdio.h>
31#include "iodefine.h"
                                 /* iodefine.h is automatically created by HEW */
32
33/* ==== Macro declaration ==== */
34#define SDRAM_DST_ADR ((void *)0x2c000000) /* External SDRAM start address
                                                                              * /
35#define SRAM_SRC_ADR ((void *)0xfff88000)
                                          /* Internal SRAM start address
36#define SIZE
                  100
                                            /* 100 bytes of data are transferred */
37
38
39#define DMA_SIZE_BYTE
                           0x0000u
40#define DMA_SIZE_WORD
                          0x0001u
41#define DMA_SIZE_LONG
                           0x0002u
42#define DMA_SIZE_LONGx4
                          0x0003u
43#define DMA_INT_DISABLE
                          0x0000u
44#define DMA_INT_ENABLE
                         0x0010u
45#define DMA_INT
                          (DMA_INT_ENABLE >> 4u)
46
47/* ==== Prototype declaration ==== */
48void main(void);
49void io_init_dma0(void *src, void *dst, size_t size, unsigned int mode);
50void io_dma0_enable(void);
51void io_dma0_stop(void);
52
53
```

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2. Sample Program Listing "main.c" (2) 54 /*""FUNC COMMENT""****** * Outline 55 : Sample Program Main *_____ 56 57 * Include : *_____ 58 59 * Declaration : void main(void); 60 *_____ : Sample program for transferring 100-byte data from on-chip RAM to external 61 * Function 62 * : SDRAM. 63 * : Completion of DMA transfer is detected through the DMA transfer-end flag. 64 * : When DMA transfer ends, the processing enters infinite loop. 65 *-----66 * Argument : void 67 *-----68 * Return Value : void 69 *-----70 * Notice :. In the sample program, absolute addresses are used to clarify 71 * : the start addresses of the data transfer source and destination. 72 * : When allocating memory areas by absolute addresses, be careful so that 73 * : they do not overlap with the sections used by user programs. 74 * :. In DMA transfer with the operand cache enabled, 75 * : coherency must be kept by disabling or writing back the cache. 76 * : In the sample program, coherency is kept because cache-disabled space is 77 * : accessed from the CPU. 79 void main(void) 80 { 81 int i; volatile unsigned char *ptr; 82 83 /* ==== Transfer source memory initialization ==== */ 84 85 ptr = SRAM_SRC_ADR; 86 for(i=0; i < SIZE; i++){</pre> 87 *ptr++ = 0x55; /* Fill the transfer source memory with 0x55 $\,$ */ } 88 89 90 /* ==== Transfer destination memory initialization ==== */ 91 ptr = SDRAM_DST_ADR; 92 for(i=0; i < SIZE; i++){</pre> 93 *ptr++ = 0; /* Clear transfer destination memory to all 0 */ 94 } 95 /* ==== DMAC initialization ==== */ 96 97 io_init_dma0(SRAM_SRC_ADR, SDRAM_DST_ADR, SIZE , DMA_SIZE_LONG | DMA_INT_DISABLE); 98 99 /* ---- Start DMA transfer ---- */ io_dma0_enable(); 100 101 /* ---- Stop DMA transfer ---- */ 102 io_dma0_stop(); 103 104 105 while(1){ 106 /* Program end */ 107 } 108 } 109

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3. Sample Program Listing "main.c" (3) 110 /*""FUNC COMMENT""****** * Outline : Initialization for DATA transfer between memory areas with DMAC 111 *_____ 112 113 * Include : #include "iodefine.h" 114 *_____ : io_init_dma0(void *src, void *dst, size_t size, unsigned int mode); 115 * Declaration 116 *_____ 117 * Function : The DMAC transfers the amount of data specified by "size". 118 : from the source address "src" to the destination address "dst." 119 * : Auto request mode is used to transfer data. 120 * : "mode" is specified for transfer size and interrupt used/not used *_____ 121 * Argument : void *src 122 : Source address : Destination address 123 : void *dst 124 : Transfer size (byte) : size_t size : unsigned int mode : Transfer mode, specifies the following with logical OR. 125 126 DMA_SIZE_BYTE(0x0000) Byte transfer : : DMA_SIZE_WORD(0x0001) Word transfer 127 : 128 DMA_SIZE_LONG(0x0002) Longword transfer * : 129 DMA_SIZE_LONGx4(0x0003) 16-byte transfer 130 : DMA_INT_DISABLE(0x0000) DMA transfer end interrupt disabled 131 : DMA_INT_ENABLE(0x0010) DMA transfer end interrupt enabled 132 * : 133 *-----* Return Value : void 134 135 *_____ : Operation is not guaranteed when the alignment of the source/destination 136 * Notice 137 : address is inconsistent. 138 : When interrupts are used, interrupt routines must be registered. 139 140 void io_init_dma0(void *src, void *dst, size_t size, unsigned int mode) 141 { 142 unsigned int ts; 143 unsigned long ie; 144 145 ts = mode & 0x3u;ie = (mode & 0x00f0u) >> 4u; 146 147 /* ==== Set standby control register 2 (STBCR2) ==== */ 148 149 CPG.STBCR2.BIT.MSTP8 = 0x0; /* Cancel module stop mode of the DMAC */ 150 151 /* ---- Set DMA channel control register ---- */ DMAC.CHCR0.BIT.DE = Oul; /* Disable DMA transfer * / 152 153 /* ---- Set DMA source address register ---- */ 154 DMAC.SAR0.LONG = (unsigned long)src; 155 156 /* ---- Set DMA reload source address register ---- */ 157 DMAC.RSAR0.LONG = (unsigned long)src; 158 159 /* ---- Set DMA destination address register ---- */ 160 DMAC.DAR0.LONG = (unsigned long)dst; 161 162 /* ---- Set DMA reload destination address register ---- */ 163 164 DMAC.RDAR0.LONG = (unsigned long)dst; 165 166 /* ---- Set DMA transfer count register ---- */



4. Sample Program Listing "main.c" (4) /* ---- Set DMA reload transfer count register ---- */ 167 168 169 switch(ts){ 170 case DMA_SIZE_BYTE: 171 DMAC.DMATCR0.LONG = size; /* Specify transfer count (1/1) */ DMAC.RDMATCR0.LONG = size; 172173 break; 174 case DMA_SIZE_WORD: 175 DMAC.DMATCR0.LONG = size >> 1u; /* Specify transfer count (1/2) */ 176 DMAC.RDMATCR0.LONG = size >> lu; 177 break; 178 case DMA_SIZE_LONG: /* Specify transfer count (1/4) */ 179 DMAC.DMATCR0.LONG = size >> 2u;DMAC.RDMATCR0.LONG = size >> 2u; 180 181 break; case DMA_SIZE_LONGx4: 182 183 DMAC.DMATCR0.LONG = size >> 4u; /* Specify transfer count (1/16) */ DMAC.RDMATCR0.LONG = size >> 4u; 184 185 break; 186 default: 187 break; 188 } 189 190 /* ---- Set DMA channel control register ---- */ DMAC.CHCR0.LONG = 0x80005400ul | (ts << 3u) | (ie << 2u) ; 191 192 /* 193 bit31 : TC DMATCR transfer:1------DMA transfer count specified in DMATC 194 bit30 : reserve 0 : RLDSAR OFF : 0-----195 bit29 Disable SAR reload function : RLDDAR OFF : 0------Disable DAR reload function 196 bit28 bit27-24 : reserve 0 197 bit23 : DO over run0 : 0-----198 Unused 199 bit22 : TL TEND low active : 0----Unused bit21 200 : reserve 0 201 bit20 : TEMASK : TE set mask : 0--Disable DMA transfer when TE bit is 202 set bit19 : HE :0-----203 Unused : HIE :0-----204 bit18 Unused : AM :0-----205 bit17 Unused 206 bit16 : AL :0-----Unused bit15-14 : DM1:0 DM0:1-----207 Increment destination address bit13-12 : SM1:0 SM0:1-----208 Increment source address bit11-8 : RS : auto request : B'0100-209 Auto request : DL : DREQ level : 0 ------210 bit7 Unused 211 bit6 : DS : DREQ select :0 Low level Unused : TB : cycle :0-----Cycle-stealing mode 212 bit5 bit4-3 : TS : transfer size:B'10---213 Longword transfer : IE : interrupt enable:0--bit2 Disable interrupts 214 : TE : transfer end------Clear TE flag 215 bit1 bit0 : DE : DMA enable bit:0-----216 Disable DMA transfer 217 */ 218 219 /* ----Set DMA operation register---- */ 220 DMAC.DMAOR.WORD &= 0xfff9u; /* AE,NMIF */



5. Sa	umple Program Listing "main.c" (5)
221	if(DMAC.DMAOR.BIT.DME == 0){ /* Enable DMA transfer on all channels */
222	DMAC.DMAOR.BIT.DME = 1;
223	}
224	
225	
226	/*""FUNC COMMENT""***********************************
227	* Outline : DMAC Actibation
228	*
	* Include : #include "iodefine.h"
	*
	* Declaration : void io_dma0_enable(void);
	*
	* Function : Performs DMA transfer
	*
	* Argument : void *
	* Return Value: void *
	* Notice : *""FUNC COMMENT END""***********************************
	void io_dma0_enable(void)
241	
243	
244	
245	
246	
247	//*""FUNC_COMMENT""***********************************
248	* Outline : DMAC Stop
249	*
250	* Include : #include "iodefine.h"
251	*
252	* Declaration : void io_dma0_stop(void);
253	*
	* Function : Checks whether the transfer is completed and stops the DMA transfer.
255	*
	* Argument : void
	*
	* Return Value: void
	*
	* Notice : *""FUNC COMMENT END""***********************************
262	void io_dma0_stop(void)
263	Υ.
265	
265	•
267	
268	
269	-
270	
271	
	/* End of File */



4. Documents for Reference

- Software Manual SH-2A, SH2A-FPU Software Manual The most up-to-date version of this document is available on the Renesas Technology Website.
- Hardware Manual SH7203 Group Hardware Manual SH7263 Group Hardware Manual The most up-to-date version of this document is available on the Renesas Technology Website.



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